MA3S781F

Silicon epitaxial planar type

For high speed switching circuits

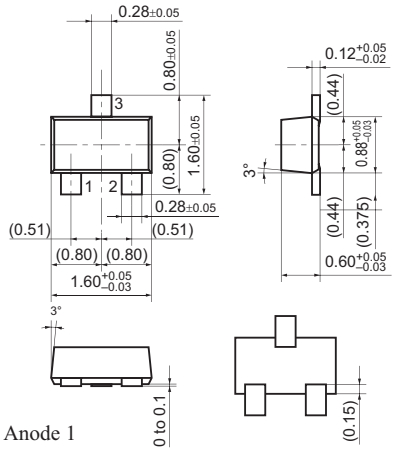
■ Features

- Optimum for high-density mounting
- Short reverse recovery time t_{rr} , optimum for high-frequency rectification

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	30	V
Maximum peak reverse voltage		V_{RM}	30	V
Forward current	Single	I_F	30	mA
	Series		20	
Peak forward current	Single	I_{FM}	150	mA
	Series		110	
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	–55 to +125	°C

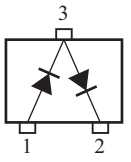
Unit: mm



1: Anode 1
2: Cathode 2
3: Cathode 1
Anode 2
EIAJ : SC-81 SSMini3-F2 Package

Marking Symbol: M1U

Internal Connection



■ Electrical Characteristics $T_a = 25°C \pm 3°C$

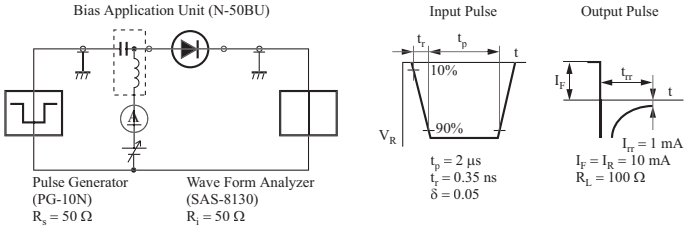
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 1 mA			0.4	V
	V_{F2}	I_F = 30 mA			1.0	
Reverse current	I_R	V_R = 30 V			300	nA
Terminal capacitance	C_t	V_R = 1 V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 10 mA, I_{rr} = 1 mA R_L = 100 Ω		1.0		ns
Detection efficiency	η	$V_{IN} = 3\ V_{(peak)}$, f = 30 MHz R_L = 3.9 kΩ, C_L = 10 pF		65		%

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

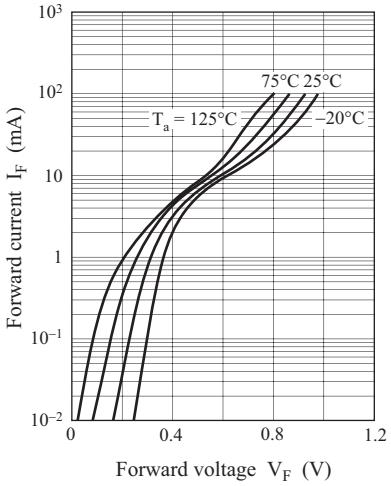
2. Absolute frequency of input and output is 2 000 MHz

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

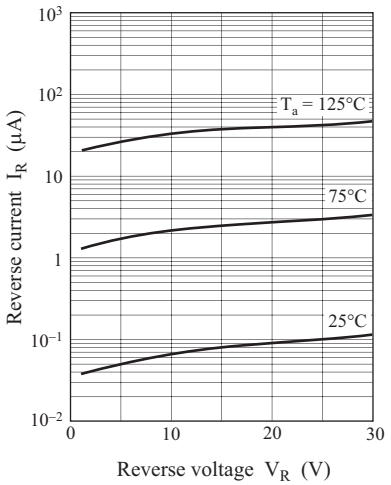
3. *: t_{rr} measurement circuit



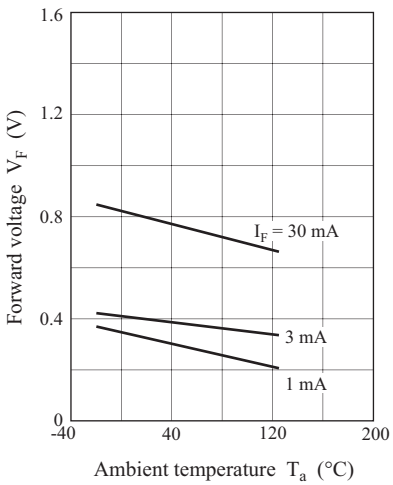
I_F — V_F



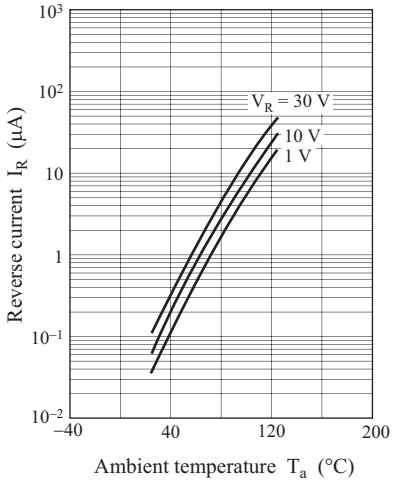
I_R — V_R



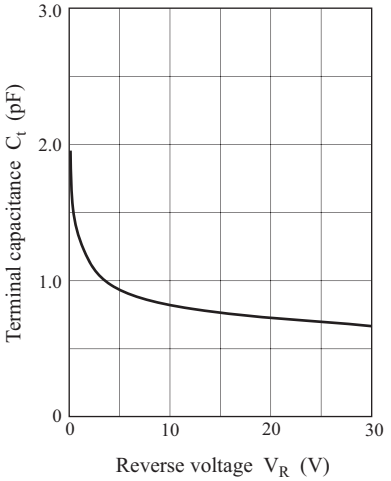
V_F — T_a



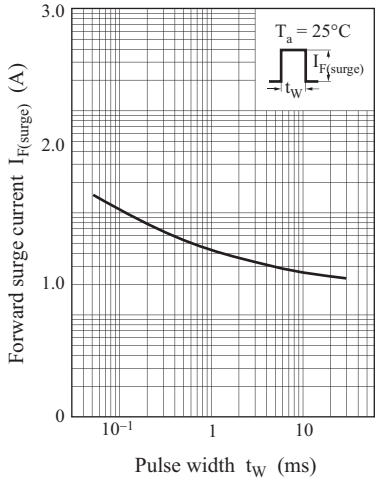
I_R — T_a



C_t — V_R



$I_{F(surge)}$ — t_W



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